

Features

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Low $R_{DS(ON)}$
- Advanced high cell density Trench technology

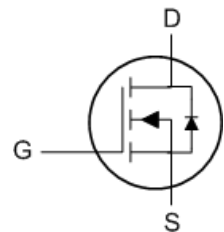
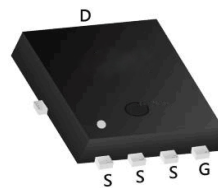
Product Summary

BVDSS	RDSON	ID
30V	6.3mΩ	52A

Description

The JHG3052 is the high cell density Trench MOSFET, which provide excellent $R_{DS(ON)}$ and gate charge for DC/DC converters application. The JHG3052 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

DFN 5X6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
$I_D @ T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	52	A
$I_D @ T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	33	A
$I_D @ T_A=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	25	A
$I_D @ T_A=70^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	20	A
I_{DM}	Pulsed Drain Current ²	125	A
EAS	Single Pulse Avalanche Energy ³	28.8	mJ
I_{AS}	Avalanche Current	24	A
$P_D @ T_C=25^{\circ}C$	Total Power Dissipation ⁴	27	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	4.6	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =20A	---	5	6.3	mΩ
		V _{GS} =4.5V , I _D =15A	---	6.9	9	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	---	2.5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =24V , V _{GS} =0V , T _J =55°C	---	---	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V , I _D =20A	---	67	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =15V , V _{GS} =4.5V , I _D =15A	---	8	---	nC
Q _{gs}	Gate-Source Charge		---	2.4	---	
Q _{gd}	Gate-Drain Charge		---	3.2	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V , V _{GS} =10V , R _G =3.3Ω I _D =15A	---	7.1	---	ns
T _r	Rise Time		---	40	---	
T _{d(off)}	Turn-Off Delay Time		---	15	---	
T _f	Fall Time		---	6	---	
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz	---	814	---	pF
C _{oss}	Output Capacitance		---	498	---	
C _{rss}	Reverse Transfer Capacitance		---	41	---	
Diode Characteristics						
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current	---	---	30	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	I _F =20A , di/dt=100A/μs ,	---	15	---	nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C	---	25	---	nC

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$ 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V$, $V_{GS}=10V$, $L=0.1mH$, $I_{AS}=24A$ 4.The power dissipation is limited by 150°C junction temperature5.The data is theoretically the same as I_D and I_S , in real applications , should be limited by total power dissipation.

Typical Characteristics

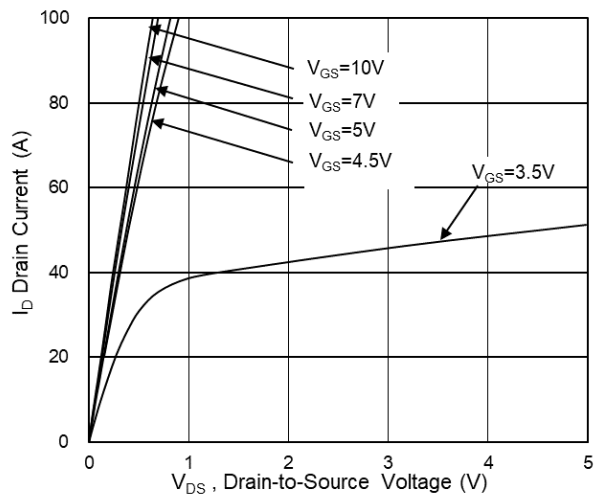


Fig.1 Typical Output Characteristics

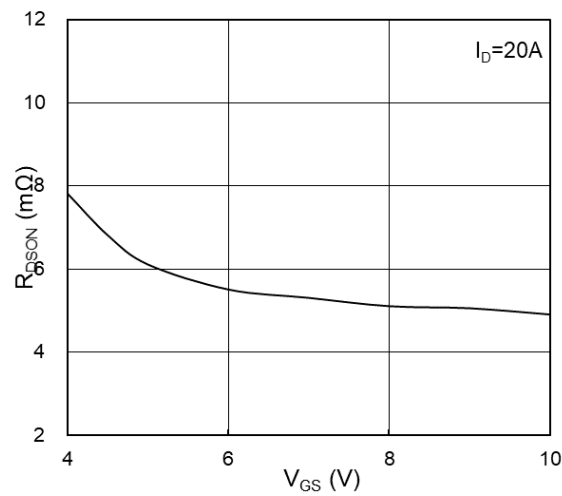


Fig.2 On-Resistance vs G-S Voltage

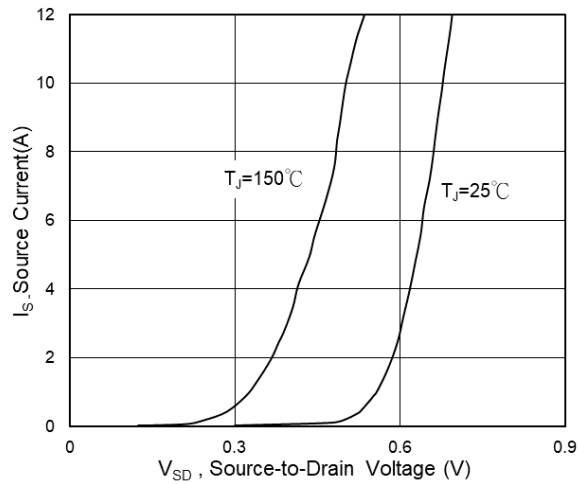


Fig.3 Source Drain Forward Characteristics

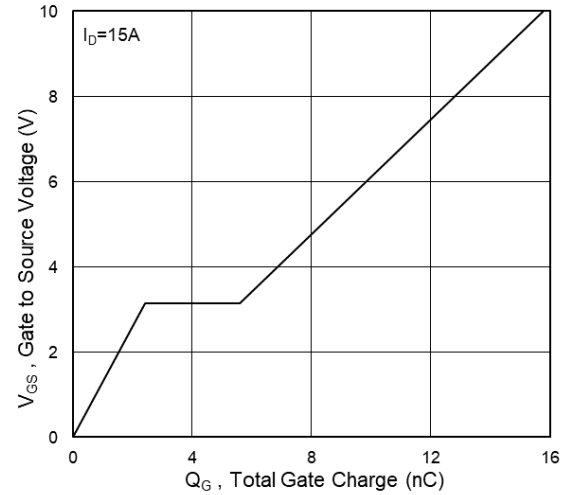


Fig.4 Gate-Charge Characteristics

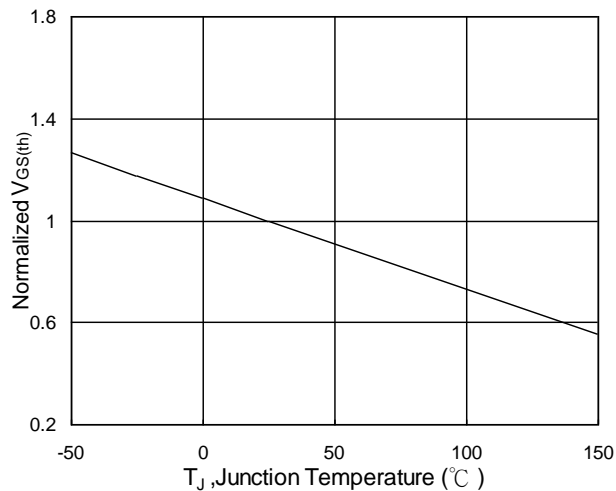


Fig.5 Normalized $V_{GS(th)}$ vs T_J

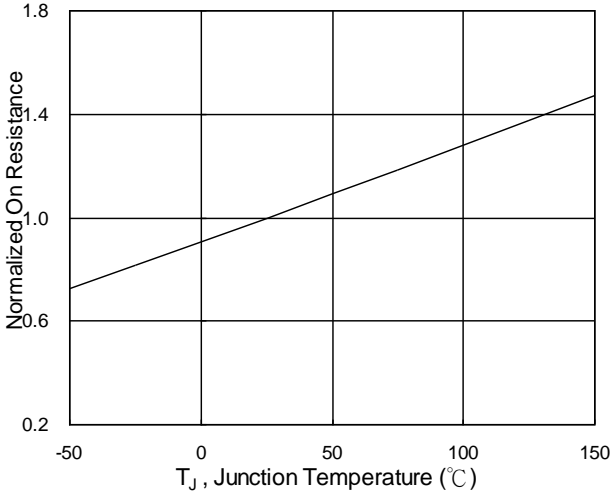


Fig.6 Normalized $R_{DS(on)}$ vs T_J

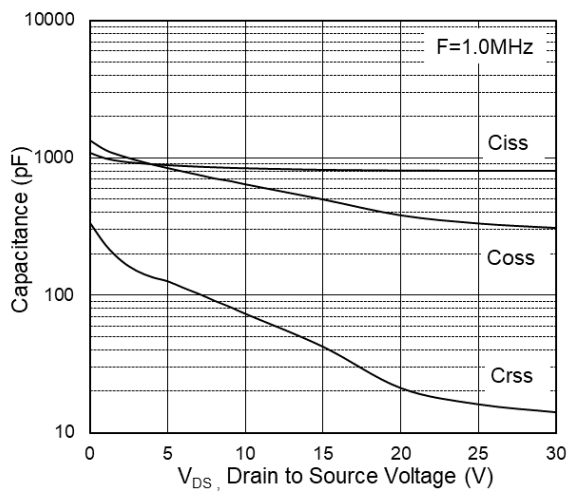


Fig.7 Capacitance

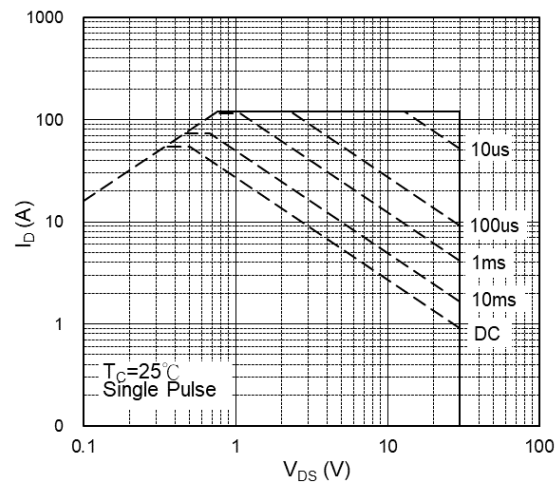


Fig.8 Safe Operating Area

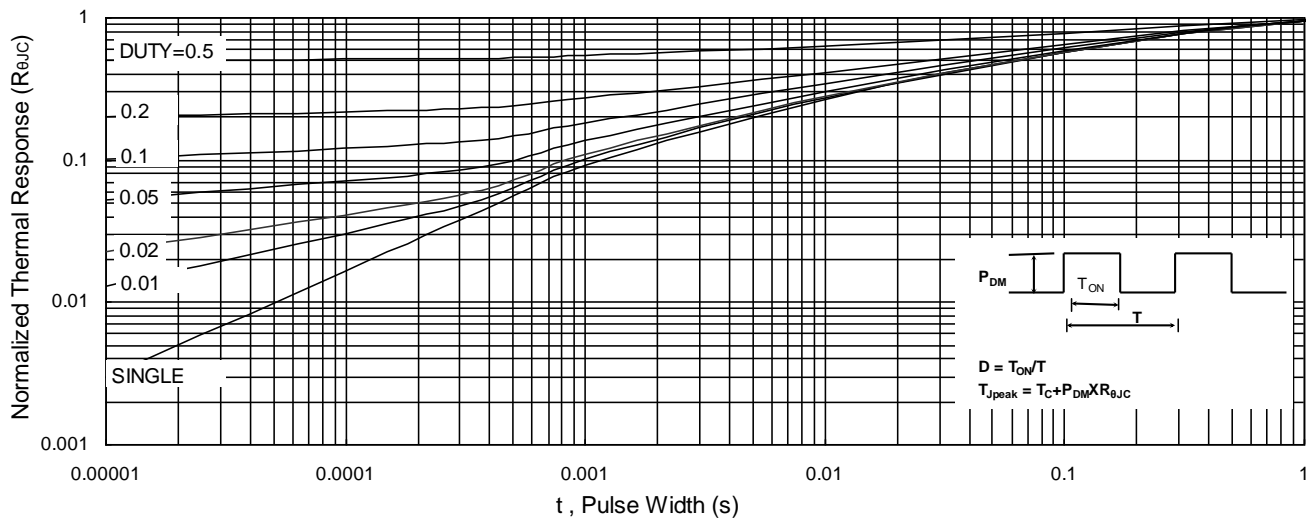


Fig.9 Normalized Maximum Transient Thermal Impedance

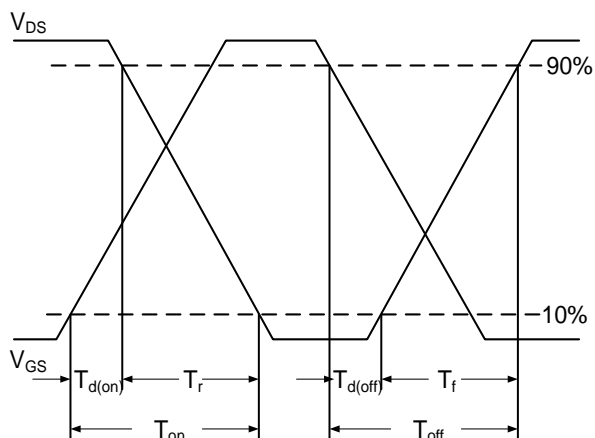


Fig.10 Switching Time Waveform

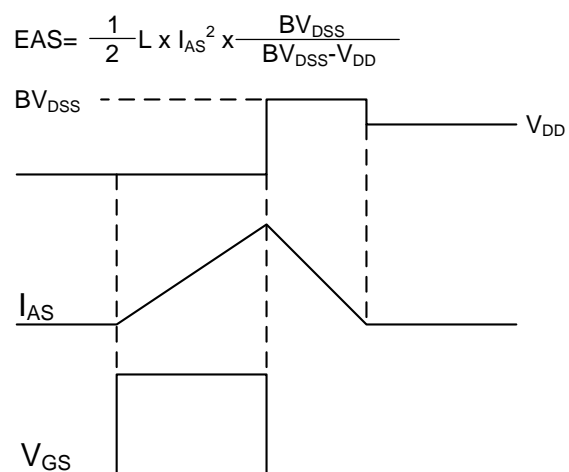
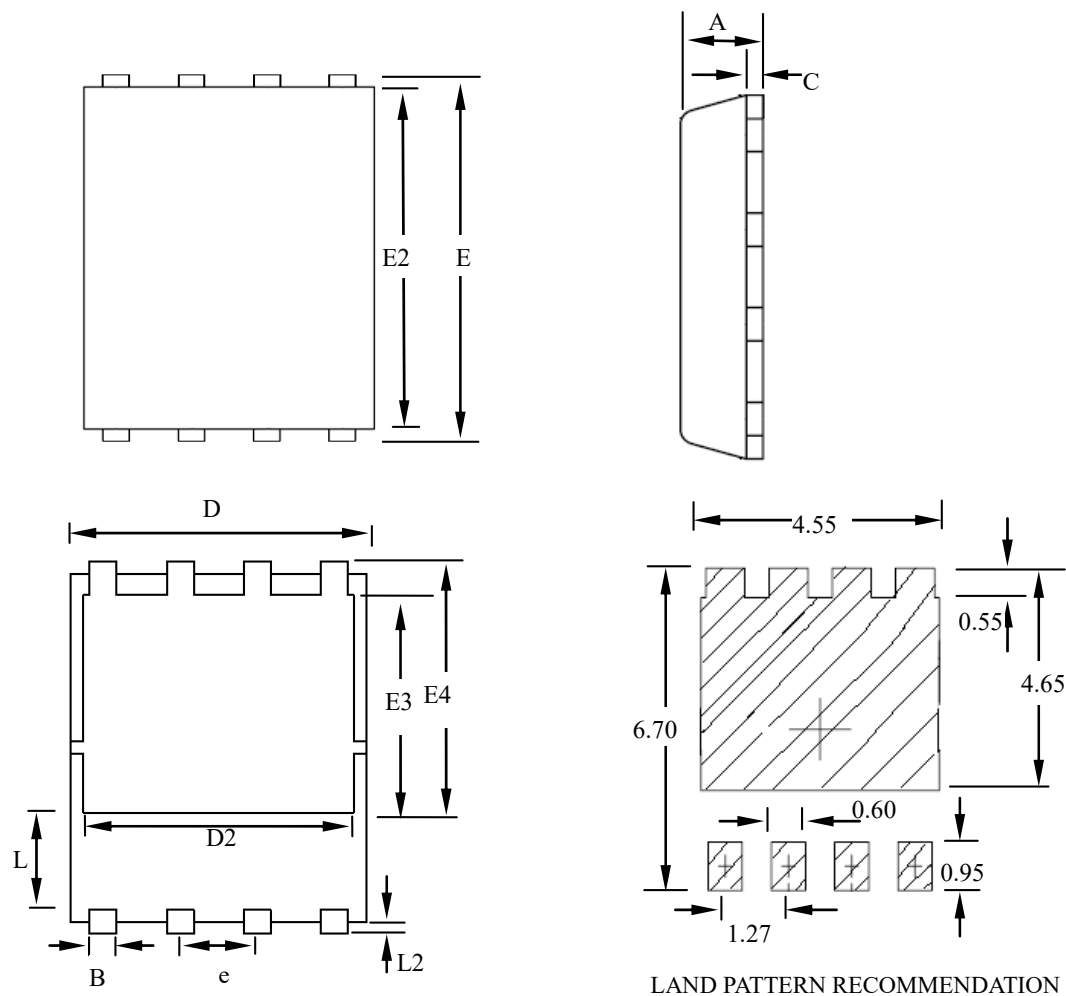


Fig.11 Unclamped Inductive Switching Waveform

DFN5×6 Outline



LAND PATTERN RECOMMENDATION



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145		0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--

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